

WHAT IS CLAIMED IS:

1. A semiconductor chip mounting component comprising:

5 (a) a support structure having a top surface, bottom surface, and a gap extending through said support structure between said surfaces;

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10 (b) a plurality of electrically conductive leads, each said lead having a connection section extending across said gap, said connection section having a first end disposed on the support structure on one side of the gap, a second end secured to said support structure on an opposite side of said gap, and a frangible section;

15 (c) at least one elongated bus disposed alongside said gap, wherein each of said leads extends across said gap and is connected to the bus.

2. The component of claim 1, wherein the gap includes a plurality of holes.

3. The component of claim 2, wherein at least one of the leads extends across each of the holes.

20 4. The component of claim 1, wherein the gap includes at least one elongated slot and wherein each of the leads extends across one of the elongated slots.

25 5. The component of claim 4, wherein at least one of said elongated buses is disposed alongside each of said elongated slots.

6. The component of claim 1, wherein the frangible sections of at least some of the leads are disposed adjacent the second ends of said leads.

30 7. The component of claim 6, wherein the frangible sections of at least some of the leads are disposed adjacent the first ends of said leads.

8. The component of claim 1, further comprising a polymeric reinforcement in contact with each said lead.

35 9. The component of claim 1, wherein the bus is comprised of a metallic material.

10. The component of claim 1, wherein the support structure includes a dielectric layer.

11. The component of claim 10, wherein the dielectric layer is flexible.

5 12. The component of claim 10, wherein the support structure further includes a compliant layer.

13. The component of claim 11, wherein the support structure includes a said dielectric layer defining a top surface of said support and said compliant layer defining a bottom surface of said support.

10 14. The component of claim 13, wherein the leads are disposed on the dielectric layer.

15 15. The component of claim 1, wherein the connection section and the frangible section of each lead are formed integrally with one another and with the associated bus, the connection section of each lead defining a pair of opposed horizontal edges, and the frangible lead section of each lead having a pair of notches extending horizontally inwardly from said opposed edges to define a neck having a width less than the width between said edges.

20 16. The component of claim 15, wherein each said lead has a second end securement section extending between the frangible section and the associated bus.

25 17. A component as claimed in claim 1, wherein said support structure includes a central portion and a peripheral portion, said gap including a plurality of elongated slots extending substantially around said central portion so that the slots are disposed between the central portion and the peripheral portion, the component including a plurality of said elongated buses arranged on said peripheral portion so that one such bus extends alongside each said slot.

30 18. The component as claimed in claim 17, wherein said buses are connected to one another so that said buses cooperatively form a hoop-like structure on said

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peripheral portion substantially surrounding said central portion and said slots.

19. The component as claimed in claim 18, wherein said slots are connected to one another to form substantially continuous channel surrounding said central portion, said central portion being connected to said peripheral portion only through said leads, whereby said central portion will be detached from said peripheral portion upon breakage of said frangible elements.

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